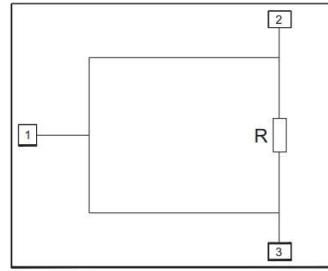


### Performance

- Frequency: 10~20GHz
- Insertion loss: 0.8dB
- Chip size: 0.9\*1.4\*0.1mm

### Function Diagram

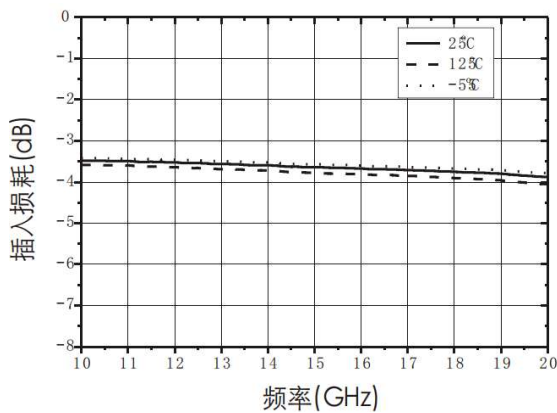


### Electrical Specifications (Ta=+25°C, 50Ω system)

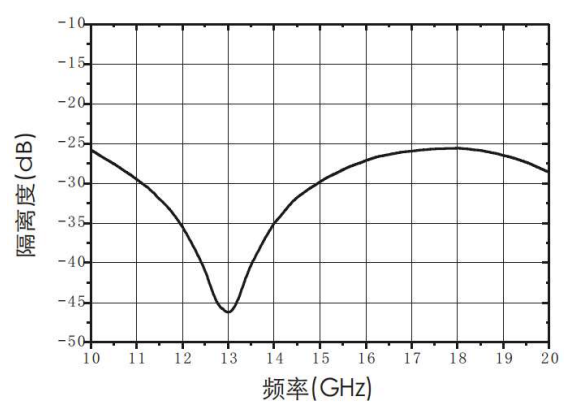
Parameter	Min	Typical	Max	Unit
Frequency Range	10~20			GHz
Insertion Loss	-	0.8	0.9	dB
Insertion Loss Ripple	-	±0.4	-	dB
Isolation	25	27	-	dB
Input Return Loss	16	20	-	dB
Output Return Loss	18	20	-	dB

### Test Curves

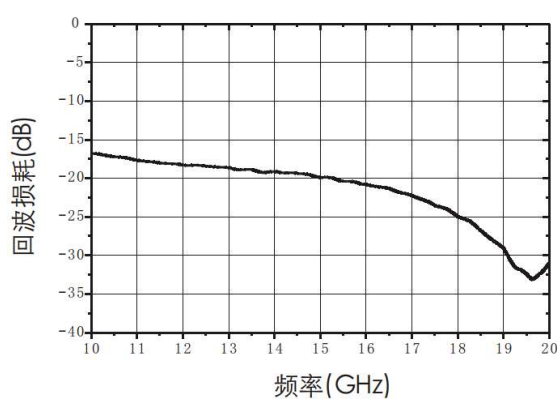
Insertion loss vs. Freq



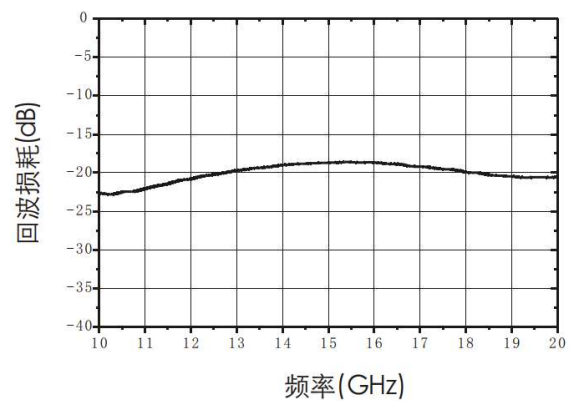
Isolation vs. Freq



Input Return Loss vs. Freq



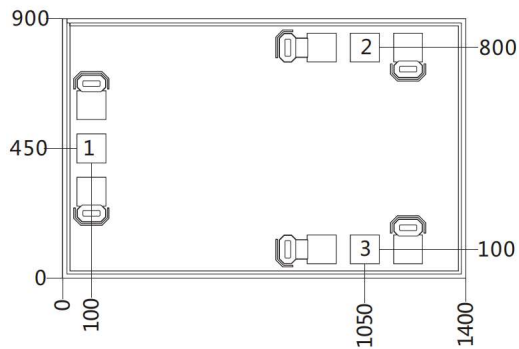
Output Return Loss vs. Freq



### Absolute Max Ratings

Parameter	Value
Input Signal Power	+33dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Static protection Grade (HBM)	Class 1C

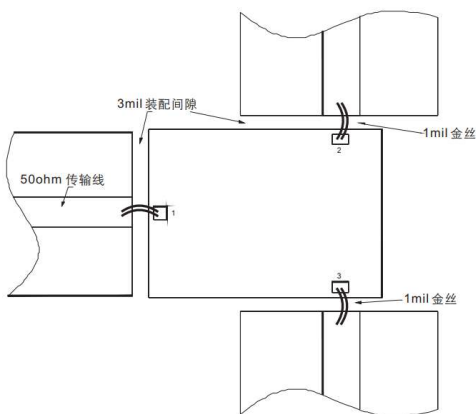
### Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated  
Pads size: 100\*100 um
5. Don't bonding on thru holds
6. Tolerance: ±50um

### Assembly Diagram



### Bonding Definition

No.	Number	Description
1	IN	RF input, 50ohm
2,3	Out1 Out2	RF output, 50ohm
	GND	Bottom must be grounded